



Material Content Data Sheet



Sales Product Name				IR38163MTRPBF		Issued		22. January 2018	
MA#				MA001688554					
Package				PG-IQFN-34-900		Weight*		118.34 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.944	4.18	4.18	41779	41779	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		110		
	non noble metal	zinc	7440-66-6	0.052	0.04		440		
	non noble metal	iron	7439-89-6	1.043	0.88		8810		
wire	non noble metal	copper	7440-50-8	42.333	35.77	36.70	357725	367085	
	noble metal	gold	7440-57-5	0.504	0.43	0.43	4262	4262	
	encapsulation	organic material	carbon black	1333-86-4	0.103	0.09		874	
encapsulation	plastics	epoxy resin	-	5.327	4.50		45010		
	inorganic material	silicondioxide	60676-86-0	46.284	39.13	43.72	391108	436992	
	leadfinish	noble metal	palladium	7440-05-3	0.001	0.00		12	
leadfinish	noble metal	gold	7440-57-5	0.002	0.00		19		
	non noble metal	nickel	7440-02-0	0.041	0.03	0.03	345	376	
	plating	noble metal	palladium	7440-05-3	0.001	0.00		12	
plating	noble metal	gold	7440-57-5	0.002	0.00		20		
	non noble metal	nickel	7440-02-0	0.042	0.04		356		
	noble metal	silver	7440-22-4	0.604	0.51	0.55	5103	5491	
solder	noble metal	silver	7440-22-4	0.132	0.11		1116		
	non noble metal	tin	7440-31-5	0.264	0.22		2232		
	non noble metal	lead	7439-92-1	4.887	4.13	4.46	41292	44640	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.004	0.00		30		
	non noble metal	zinc	7440-66-6	0.014	0.01		119		
	non noble metal	iron	7439-89-6	0.282	0.24		2385		
heat sink CLIP	non noble metal	copper	7440-50-8	11.460	9.68	9.93	96841	99375	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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